#### 501807082 02/02/2012

#### PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

# **CONVEYING PARTY DATA**

Name	Execution Date
Chung Kun CHO	01/30/2012
Kalinina FEDOSYA	01/30/2012
Kovalev MIKHAIL	01/30/2012
Sang Mock LEE	01/30/2012

### RECEIVING PARTY DATA

Name:	SAMSUNG ELECTRONICS CO., LTD.	
Street Address:	416, Maetan-dong, Yeongtong-gu	
City:	Suwon-si, Gyeonggi-do	
State/Country:	REPUBLIC OF KOREA	

## PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13364062

### **CORRESPONDENCE DATA**

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Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via

US Mail.

Cantor Colburn LLP Correspondent Name: Address Line 1: 20 Church Street

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ATTORNEY DOCKET NUMBER:	PNK0877US
NAME OF SUBMITTER:	Leah M. Reimer

Total Attachments: 2 source=66K0370#page1.tif source=66K0370#page2.tif

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**PATENT** 

REEL: 027640 FRAME: 0024

#### <u>ASSIGNMENT</u>

WHEREAS WE, Chung Kun CHO of LD Koron Apt. 104-1502, Guwoon-dong, Gwonsun-gu, Suwon-si, Gyeonggi-do, Republic of Korea; Kalinina FEDOSYA of 902-1805, Byeokjeokgol 9-danji Jugong Apt., Yeongtong 2-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Republic of Korea; Kovalev MIKHAIL of 403-704, Cheongmyeong Maeul 4-danji Apt., Yeongtong 1-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Republic of Korea; and Sang Mock LEE of Hyundai Morningside 2-cha Apt. 103-401, Bora-ri, Giheung-eup, Yongin-si, Gyeonggi-do, Republic of Korea (hereinafter collectively referred to as the "ASSIGNORS"), have invented certain new and useful improvements in:

# POLYAMIDE BLOCK COPOLYMER, ARTICLE INCLUDING SAME, AND DISPLAY DEVICE INCLUDING THE ARTICLE

(hereinafter referred to as the "**INVENTION**") which claims priority to Korean Application No. 10-2011-0047491, filed on 19 May 2011; and for which we are about to file an application for a United States Patent (hereinafter collectively referred to as the "**APPLICATIONS**");

AND WHEREAS, SAMSUNG ELECTRONICS CO., LTD. (hereinafter referred to as "ASSIGNEE"), a corporation organized and existing under the laws of the Country of KOREA, having a place of business at 416, Maetan-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Republic of Korea, is desirous of acquiring an interest in any and all countries, in and to the INVENTION, the APPLICATIONS, and any and all Patents to be obtained therefor;

NOW THEREFORE, TO ALL WHOM IT MAY CONCERN, be it known that for good and valuable consideration, the receipt of which is hereby acknowledged, we, the ASSIGNORS, have assigned and transferred, and hereby assign and transfer unto ASSIGNEE, the entire right, title and interest in and to the INVENTION, the APPLICATIONS, and any and all Patents that may be issued therefrom, in any and all countries, including any and all revivals, refilings, continuations, continuations-in-part, divisions and reissues thereof, to ASSIGNEE; and we do hereby agree that we will execute all papers necessary in connection with any and all patent applications when called upon to do so by ASSIGNEE, its successors or assigns, and that we will, at the cost and expense

-1/2-

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of ASSIGNEE, fully assist and cooperate in all matters in connection with any and all patent applications and Patents issuing thereon.

The undersigned declare that all statements made herein of his own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the APPLICATIONS or any Patents issuing thereon.

Date:	2012.1.30	j.h.	L.S.
		Chung Kun CHO	
Date:	2012-1.30	k	L.S.
		Kalinina FEDOSYA	
Date:	2012.1.30	Maf	L.S.
		Kovalev MIKHAIL	
Date:	2012.1.30	My mor les	L.S.
		Sang Mock LEE	
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